

RZ/T2M Group

Encoder I/F Configuration Library

Summary

This document describes the library packages for the RZ/T2M Encoder I/F Configuration Library. This package cannot be used by itself. Obtain Encoder I/F application package (A-format®, FA-CODER®, HIPERFACE DSL®, etc.), and use the file in this package incorporating with the sample software that you obtained.

Functionality Checked Device

RSK+RZT2M Board (RTK9RZT2M0C00000BE)

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HIPERFACE DSL is a registered trademark of SICK AG.

1. Package Contents

This package includes following contents.

1.1 Software

- Library

No.	Title	Version number
1	RZ/T2M Encoder I/F Configuration Library	2.00

1.2 Document

No.	Document name	Version	File name
1	RZ/T2M Group Encoder I/F Configuration Library Release Note	2.00	(j) r01an6365jj0200-rzt2m.pdf (e) r01an6365ej0200-rzt2m.pdf (this document)
2	RZ/T2M Group Encoder I/F Configuration Library User's Manual	2.00	(j) r01us0563jj0200-rzt2m-encoder.pdf (e) r01us0563ej0200-rzt2m-encoder.pdf

2. File Structure

The file structure and contents of this package are detailed below.

Top

```
|— r01an6365jj0200_rzt2m.pdf
|— r01an6365ej0200_rzt2m.pdf
└─ workspace
    └─ Software
        └─ lib
            └─ ecl
                └─ r_ecl_rzt2_gcc.a : Encoder I/F Configuration Library (for e2 studio)
                └─ r_ecl_rzt2_iar.a : Encoder I/F Configuration Library (for IAR)
                └─ r_ecl_rzt2_if.h : Encoder I/F Configuration Library Header (Common)
    └─ Documents
        └─ r01us0563jj0200_rzt2m-encoder.pdf
        └─ r01us0563ej0200_rzt2m-encoder.pdf
```

3. About Encoder I/F Configuration Library

This section describes information to use a set of Encoder I/F Configuration Library.

3.1 Software Information

3.1.1 Base OS

This library is OS-independent.

3.1.2 Memory Size

Items		Memory Size	
		EWARM [kBytes]	e ² studio [kBytes]
Encoder I/F Configuration Library	Code	4.4	14.1
	Data (with initial value)	0.3	0.3
	Data (without initial value)	0.1	0.2
	Constant Data	0.0	0.0

3.2 Hardware Information

3.2.1 Device

RZ/T2M

3.2.2 Target Board

(1) Board Name

RSK+RZT2M (RTK9RZT2M0C00000BE)

(2) Setting of the Target Board

The target board settings are as follows.

SW4-1: ON

SW4-2: ON when using serial flash Boot, OFF when using NOR flash Boot.

SW4-3: ON

SW4-4: ON

SW4-5: OFF

3.3 Tool Information

3.3.1 Build Environment

Package type	Build environment
IAR version	IAR Embedded Workbench® for ARM v9.50.1 RENESAS RZ/T2 Flexible Software Package v2.0.0
GCC version	RENESAS e ² studio 2024-01.1 GNU ARM Embedded Toolchain 12.2.1.arm-12-24 RENESAS RZ/T2 Flexible Software Package v2.0.0

IAR Embedded Workbench is a registered trademark of IAR Systems.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Apr.08.22	-	First Edition issued
1.10	May 20.22	2, 3	Correct 2-tile operation of the RZ/T2M Encoder I/F Configuration Library. Update version number to 1.10.
1.20	Jun.02.22	2, 3 4	Update Library and Release Note version number to 1.20. Update build environment to use Flexible Software Package v1.0.0.
1.30	Sep.29.22	2, 3	Correct to remove out of range access in RZ/T2M Encoder I/F Configuration Library R_ECL_Start() function. Update Library and Release Note version number to 1.30.
1.40	Feb.3.23	2, 3	Correct to remove out of range access in RZ/T2M Encoder I/F Configuration Library R_ECL_UnConfigure () function. Corrected the problem that write access to ROM area occurs when configuration data is placed in ROM area. Update Library and Release Note version number to 1.40.
1.50	May 31.23	1, 4 2, 3	Append section 3.1.2 for memory size information. Update Release Note version number to 1.50
1.60	Sep.29.23	1, 4 4 4 2, 3	Update target board name. Update build environment to use Flexible Software Package v1.3.0. Update memory size information. Update Library version number to 1.50 and Release Note version number to 1.60.
2.00	Jun 7.24	1, 4 4 4 2, 3	Update description of the board name. Update build environment to use Flexible Software Package v2.0.0. Update memory size information. Update Library, User's Manual and Release Note version number to 2.00.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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